



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



### Description

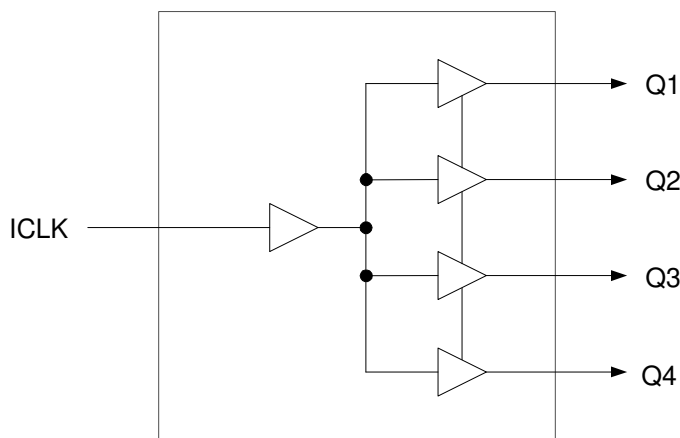
The 74FCT38074S is a low skew, single input to four output, clock buffer. The 74FCT38074S has best in class additive phase Jitter of sub 50 fsec.

IDT makes many non-PLL and PLL based low skew output devices as well as Zero Delay Buffers to synchronize clocks. Contact us for all of your clocking needs.

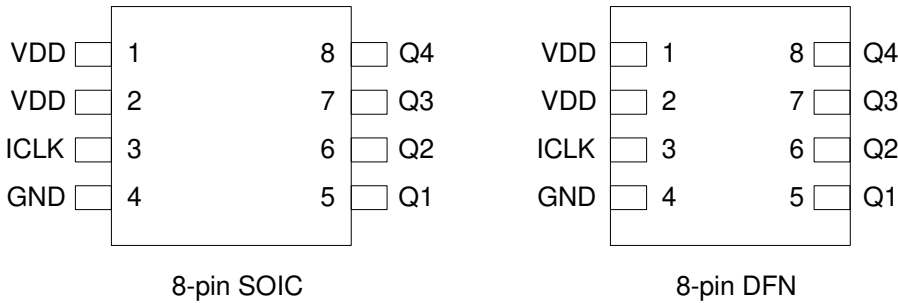
### Features

- Low additive phase jitter RMS: 50fs
- Extremely low skew outputs (50ps)
- Low cost clock buffer
- Packaged in 8-pin SOIC and 8-pin DFN, Pb-free
- Input/Output clock frequency up to 200 MHz
- Low power CMOS technology
- Operating voltages of 1.8V to 3.3V
- Extended temperature range (-40° to +105°C)

### Block Diagram



## Pin Assignments



## Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	VDD	Power	Connect to +1.8V, +2.5 V, or +3.3 V.
2	VDD	Power	Connect to +1.8V, +2.5 V, or +3.3 V.
3	ICLK	Input	Clock input.
4	GND	Power	Connect to ground.
5	Q1	Output	Clock output 1.
6	Q2	Output	Clock Output 2.
7	Q3	Output	Clock Output 3.
8	Q4	Output	Clock Output 4.

## External Components

A minimum number of external components are required for proper operation. A decoupling capacitor of 0.01 $\mu$ F should be connected between VDD on pins 1 and 2, and GND on pin 4, as close to the device as possible. A 33 $\Omega$  series terminating resistor may be used on each clock output if the trace is longer than 1 inch.

To achieve the low output skew that the 74FCT38074S is capable of, careful attention must be paid to board layout. Essentially, all four outputs must have identical terminations, identical loads and identical trace geometries. If they do not, the output skew will be degraded. For example, using a 30 $\Omega$  series termination on one output (with 33 $\Omega$  on the others) will cause at least 15 ps of skew.

## Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 74FCT38074S. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	3.465V
Outputs	-0.5 V to VDD+0.5 V
ICLK	3.465V
Ambient Operating Temperature (extended)	-40° to +105°C
Storage Temperature	-65° to +150°C
Junction Temperature	125°C
Soldering Temperature	260°C

## Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Units
Ambient Operating Temperature (extended)	-40		+105	°C
Power Supply Voltage (measured in respect to GND)	+1.71		+3.465	V



## DC Electrical Characteristics

(VDD = 1.8V, 2.5V, 3.3V)

**VDD=1.8V ±5%** , Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		1.71		1.89	V
Input High Voltage, ICLK	V <sub>IH</sub>	Note 1	0.7xVDD		VDD	V
Input Low Voltage, ICLK	V <sub>IL</sub>	Note 1			0.3xVDD	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -10 mA	1.3			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 10 mA			0.35	V
Operating Supply Current	IDD	No load, 135 MHz		13		mA
Nominal Output Impedance	Z <sub>O</sub>			17		Ω
Input Capacitance	C <sub>IN</sub>	ICLK		5		pF

Notes: 1. Nominal switching threshold is VDD/2

**VDD=2.5 V ±5%**, Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		2.375		2.625	V
Input High Voltage, ICLK	V <sub>IH</sub>	Note 1	0.7xVDD		VDD	V
Input Low Voltage, ICLK	V <sub>IL</sub>	Note 1			0.3xVDD	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -16 mA	1.8			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 16 mA			0.5	V
Operating Supply Current	IDD	No load, 135 MHz		18		mA
Nominal Output Impedance	Z <sub>O</sub>			17		Ω
Input Capacitance	C <sub>IN</sub>	ICLK		5		pF

**VDD=3.3 V ±5%** , Ambient temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		3.15		3.45	V
Input High Voltage, ICLK	V <sub>IH</sub>	Note 1	0.7xVDD		VDD	V
Input Low Voltage, ICLK	V <sub>IL</sub>	Note 1			0.3xVDD	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -25 mA	2.2			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 25 mA			0.7	V
Operating Supply Current	IDD	No load, 135 MHz		22		mA
Nominal Output Impedance	Z <sub>O</sub>			17		Ω
Input Capacitance	C <sub>IN</sub>	ICLK		5		pF

## AC Electrical Characteristics

(VDD = 1.8V, 2.5V, 3.3V)

**VDD = 1.8V ±5%**, Ambient Temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t <sub>OR</sub>	0.36 to 1.44 V, C <sub>L</sub> =5 pF		0.6	1.0	ns
Output Fall Time	t <sub>OF</sub>	1.44 to 0.36 V, C <sub>L</sub> =5 pF		0.6	1.0	ns
Start-up Time	t <sub>START-UP</sub>	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay		Note 1	1.5	2.5	4	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew		Rising edges at VDD/2, Note 2		50	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps

**VDD = 2.5 V ±5%**, Ambient Temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t <sub>OR</sub>	0.5 to 2.0 V, C <sub>L</sub> =5 pF		0.6	1.0	ns
Output Fall Time	t <sub>OF</sub>	2.0 to 0.5 V, C <sub>L</sub> =5 pF		0.6	1.0	ns
Start-up Time	t <sub>START-UP</sub>	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay		Note 1	1.8	2.5	4.5	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew		Rising edges at VDD/2, Note 2		50	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps

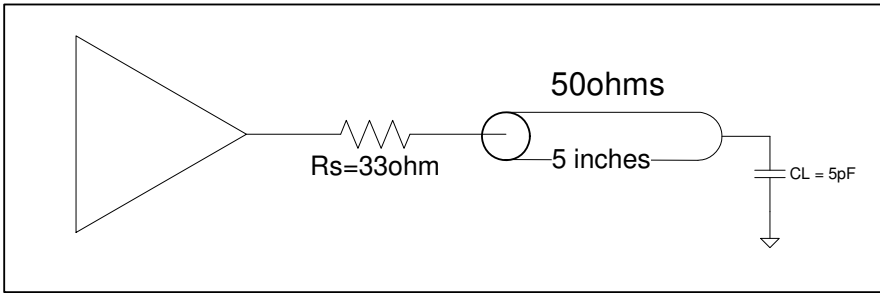
**VDD = 3.3 V ±5%**, Ambient Temperature -40° to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t <sub>OR</sub>	0.66 to 2.64 V, C <sub>L</sub> =5 pF		0.6	1.0	ns
Output Fall Time	t <sub>OF</sub>	2.64 to 0.66 V, C <sub>L</sub> =5 pF		0.6	1.0	ns
Start-up Time	t <sub>START-UP</sub>	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay		Note 1	1.5	2.5	4	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12kHz-20MHz			0.05	ps
Output to Output Skew		Rising edges at VDD/2, Note 2		50	65	ps
Device to Device Skew		Rising edges at VDD/2			200	ps

Notes:

1. With rail to rail input clock
2. Between any 2 outputs with equal loading.
3. Duty cycle on outputs will match incoming clock duty cycle. Consult IDT for tight duty cycle clock generators.

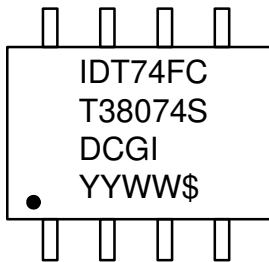
## Test Load and Circuit



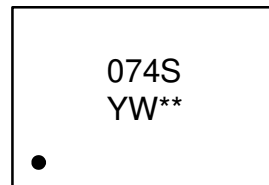
## Thermal Characteristics (8SOIC)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	$\theta_{JA}$	Still air		150		$^{\circ}\text{C}/\text{W}$
	$\theta_{JA}$	1 m/s air flow		140		$^{\circ}\text{C}/\text{W}$
	$\theta_{JA}$	3 m/s air flow		120		$^{\circ}\text{C}/\text{W}$
Thermal Resistance Junction to Case	$\theta_{JC}$			40		$^{\circ}\text{C}/\text{W}$

## Marking Diagrams



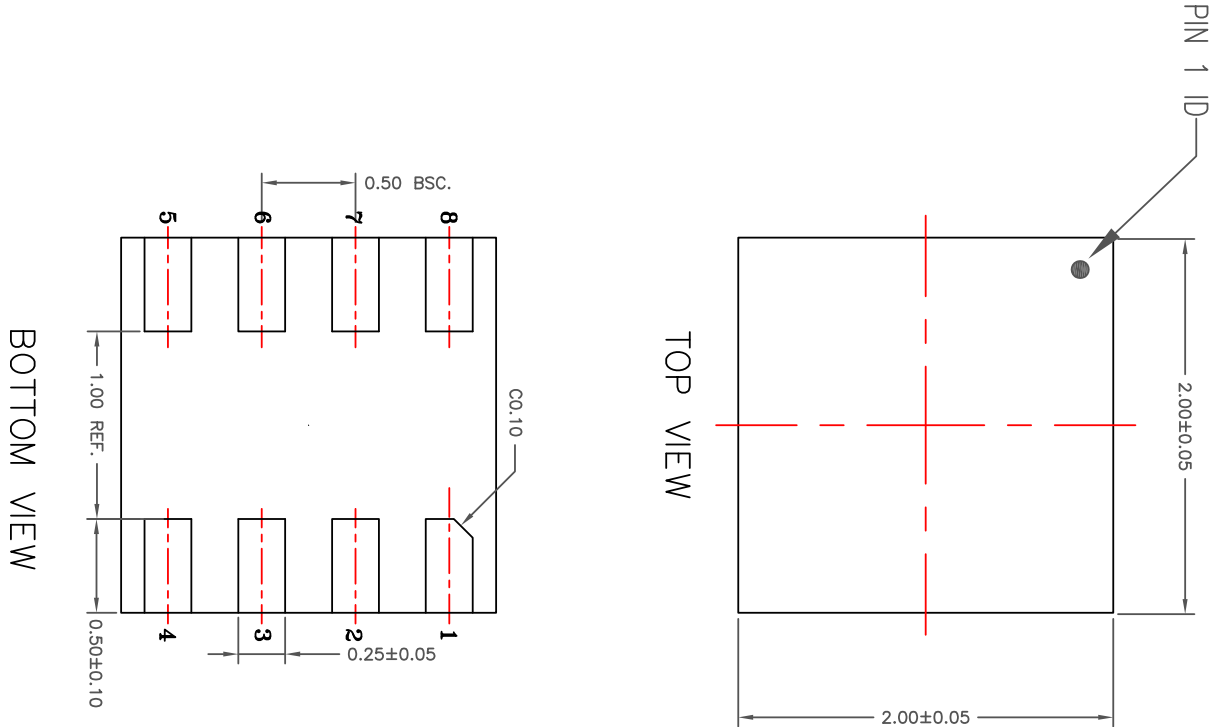
8-pin SOIC



8-pin DFN

### Notes:

1. “\*\*” is the lot number.
2. “YYWW” or “YW” are the last digits of the year and week that the part was assembled.
- 3 “G” denotes RoHS compliant package.
4. “\$” denotes mark code.
5. “I” denotes extended temperature range device.

**Package Outline and Package Dimensions (8-pin DFN, 2mm x 2mm Body, 0.5mm pitch)**

**NOTES:**

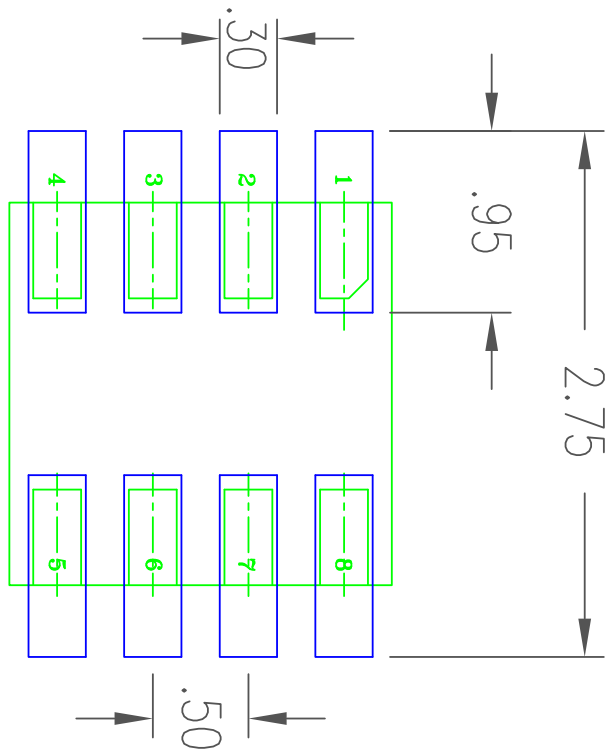
1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
2. ALL DIMENSIONS ARE IN MILLIMETERS

REVISIONS		
REV	DESCRIPTION	DATE
00	INITIAL RELEASE	09/18/14

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XXXX ±		6024 SILVER CREEK VALLEY ROAD San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 492-8674 www.idt.com	
APPROVALS	DATE	TITLE	SIZE
DRAWN: <i>024G</i> 09/10/14 CHECKED: <i>76ad</i> 09/10/14 XXXX		CMC8 PACKAGE OUTLINE 2.0 X 2.0 mm BODY 0.5mm PITCH VQFN	C
DO NOT SCALE DRAWING		DRAWING No. PSC-4490	REV 00
		SHEET 1 OF 2	



**Package Outline and Package Dimensions, cont. (8-pin DFN, 2mm x 2mm Body, 0.5mm pitch)**



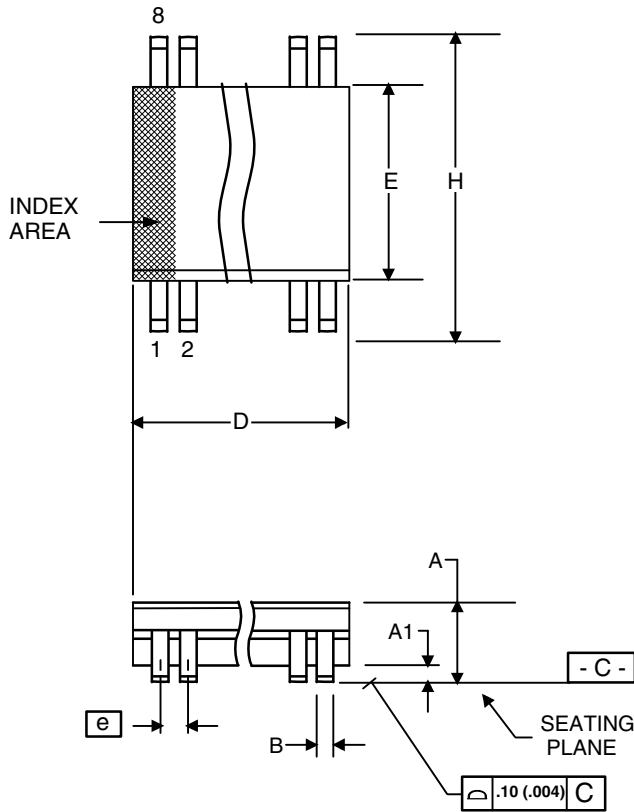
RECOMMENDED LAND PATTERN DIMENSION

- NOTES:
1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.
  2. TOP DOWN VIEW. AS VIEWED.
  3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
  4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
  5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR MOUNT DESIGN AND LAND PATTERN.

REVISIONS		
REV	DESCRIPTION	DATE
00	INITIAL RELEASE	09/18/14

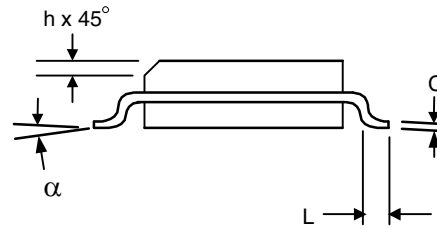
TOLERANCES UNLESS SPECIFIED		6024 SILVER CREEK, VA San Jose, CA 95138 PHONE: (408) 284-82 FAX: (408) 492-8674	
DECIMAL	ANGULAR	DRAWN: <i>QAC</i> 09/10/14 CHECKED:	
XXX±	±	TITLE: QM8 PACKAGE OUTLINE SIZE: 2.0 X 2.0 mm BODY 0.5 mm PITCH VFOFN	
XXXX±		APPROVALS:	DATE:
		SIZE: C	DRAWING No. PSC-4490
		DO NOT SCALE DRAWING	
			SHEET

## Package Outline and Package Dimensions (8-pin SOIC, 150 Mil. Narrow Body)



Symbol	Millimeters		Inches*	
	Min	Max	Min	Max
A	1.35	1.75	.0532	.0688
A1	0.10	0.25	.0040	.0098
B	0.33	0.51	.013	.020
C	0.19	0.25	.0075	.0098
D	4.80	5.00	.1890	.1968
E	3.80	4.00	.1497	.1574
e	1.27 BASIC		0.050 BASIC	
H	5.80	6.20	.2284	.2440
h	0.25	0.50	.010	.020
L	0.40	1.27	.016	.050
a	0°	8°	0°	8°

\*For reference only. Controlling dimensions in mm.



## Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
74FCT38074SDCGI	see page 6	Tubes	8-pin SOIC	-40° to +105°C
74FCT38074SDCGI8		Tape and Reel	8-pin SOIC	-40° to +105°C
74FCT38074SCMGI		Cut Tape	8-pin DFN	-40° to +105°C
74FCT38074SCMGI8		Tape and Reel	8-pin DFN	-40° to +105°C

“G” after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

## Revision History

Rev.	Date	Originator	Description of Change
A	03/18/15	B. Chandhoke	Initial release.



**Corporate Headquarters**  
6024 Silver Creek Valley Road  
San Jose, CA 95138 USA

**Sales**  
1-800-345-7015 or 408-284-8200  
Fax: 408-284-2775  
www.IDT.com

**Tech Support**  
email: [clocks@idt.com](mailto:clocks@idt.com)

DISCLAIMER Integrated Device Technology, Inc. (IDT) and its subsidiaries reserve the right to modify the products and/or specifications described herein at any time and at IDT's sole discretion. All information in this document, including descriptions of product features and performance, is subject to change without notice. Performance specifications and the operating parameters of the described products are determined in the independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in applications involving extreme environmental conditions or in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are registered trademarks of IDT. Product specification subject to change without notice. Other trademarks and service marks used herein, including protected names, logos and designs, are the property of IDT or their respective third party owners.

Copyright ©2015 Integrated Device Technology, Inc.. All rights reserved.